

CHIPBOND

2026Q I

封測產業

Most IC
ASE, SPIL, Amkor

打線 > 70%

Primary interconnecting method

凸塊

Au

Solder Bumps
CPU and Graphic
Intel and TSMC

Gold Bump
LCD Driver IC, RFID
Chipbond, Nepes

金凸塊



Applications

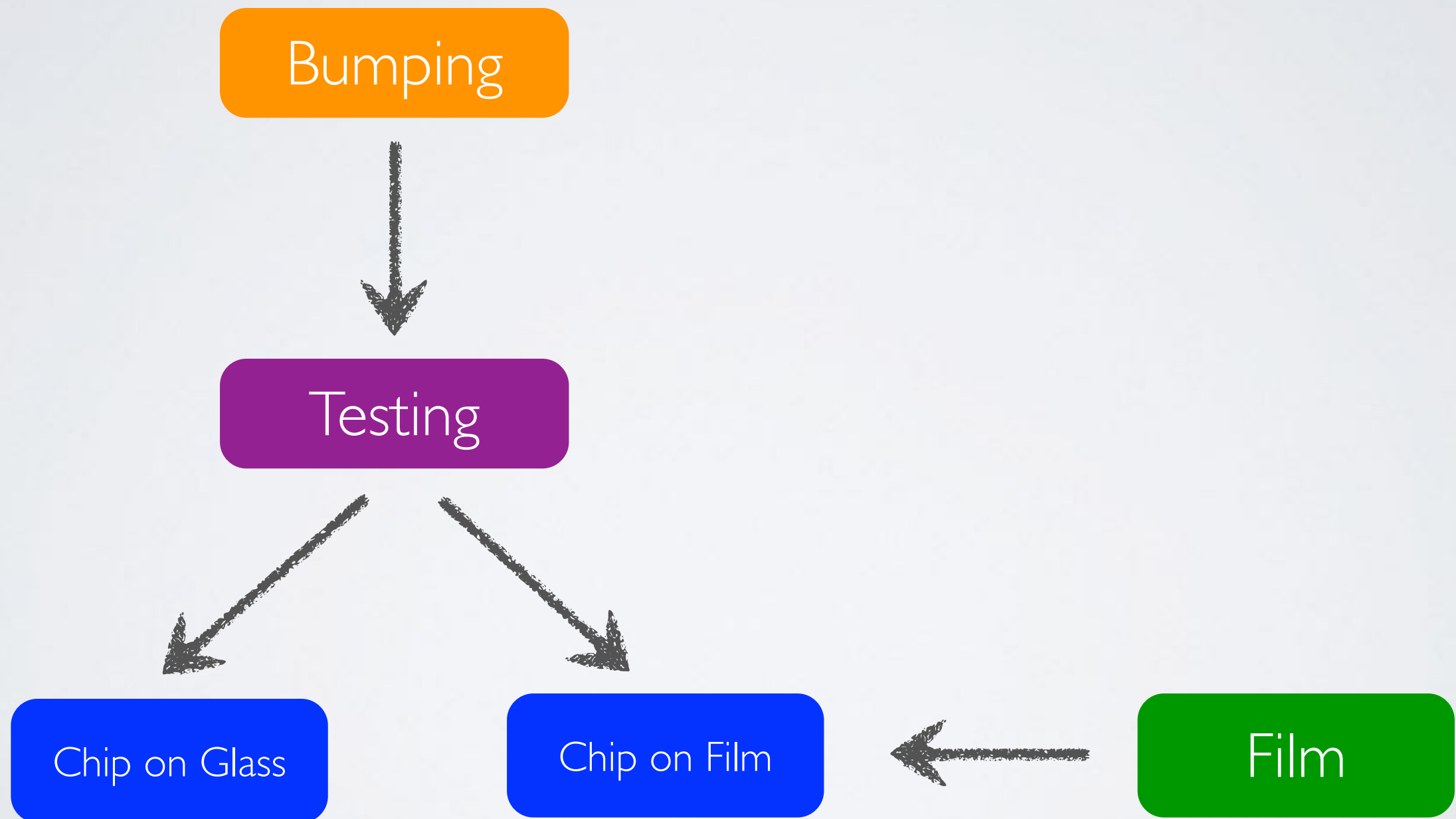
Display Driver IC

RF Front End

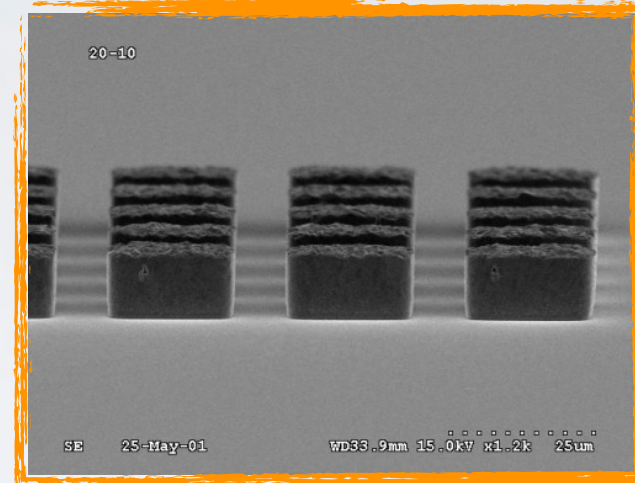
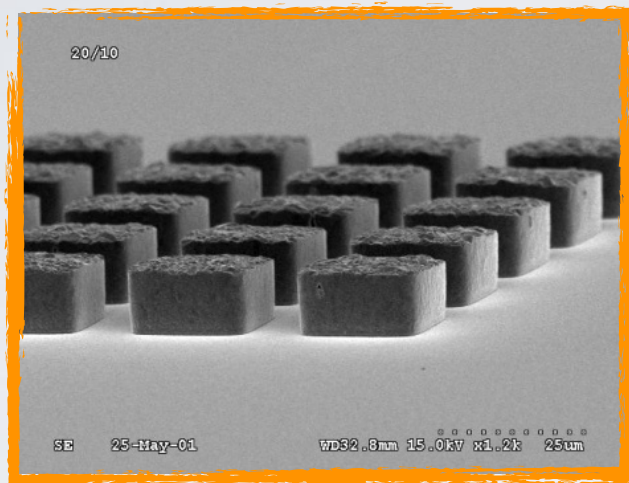
Smart Card

Finger Print Sensor

生產流程



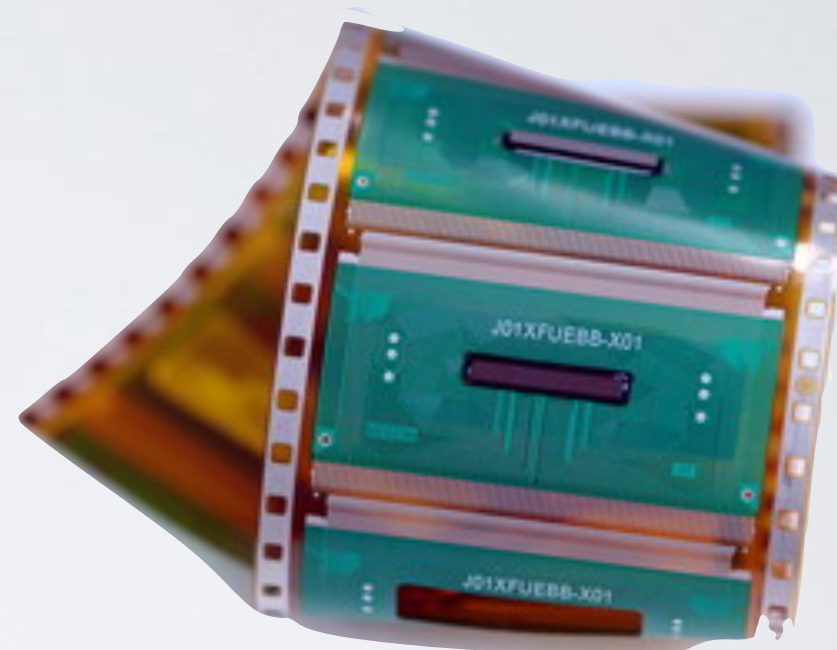
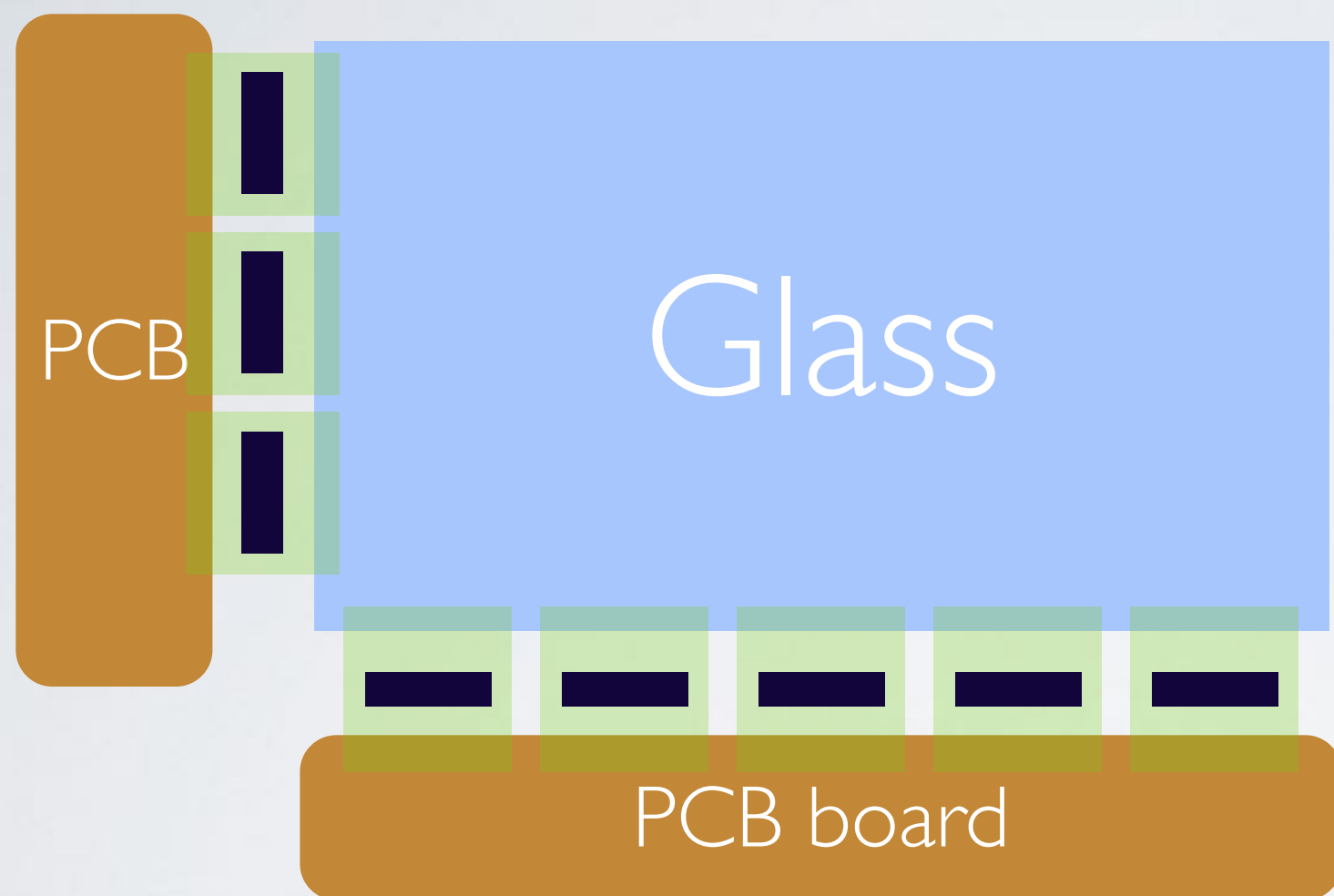
GOLD BUMPING



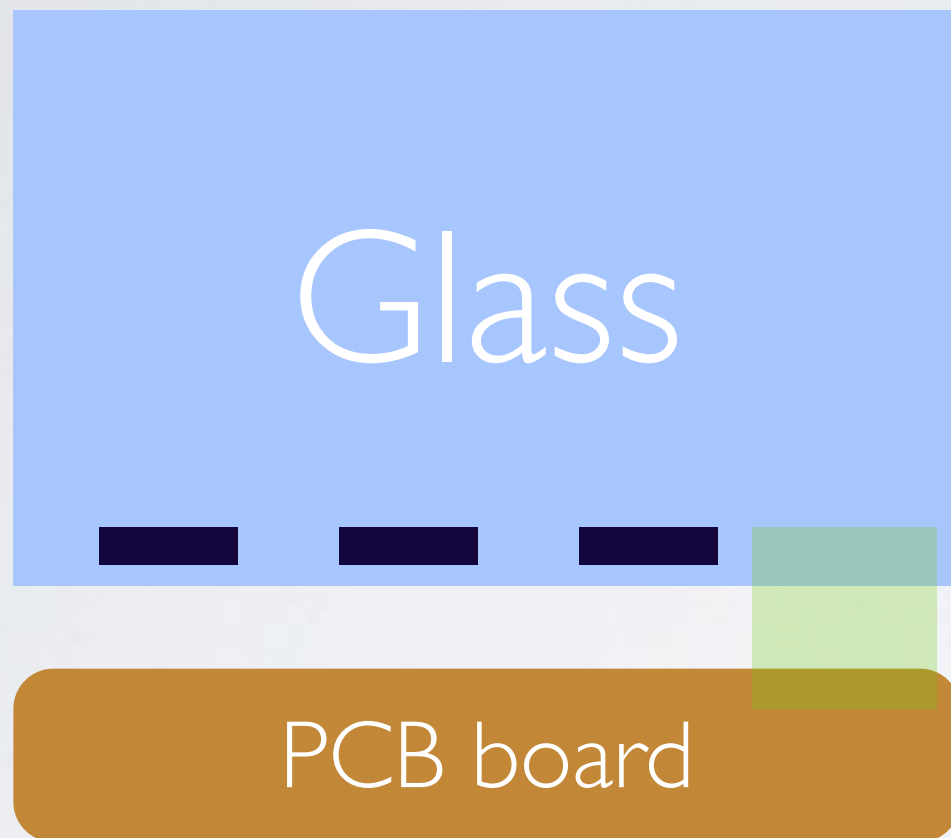
Interconnect between IC and Substrate

Has to be gold for driver IC

CHIP ON FILM



CHIP ON GLASS



	TV	Phone	NB/PC	RF
Bumping	8''	12''	8''	8''
Testing	v	v	v	v
Chip on Glass		v	v	
Chip on Film	v	v		
Film	v	v		

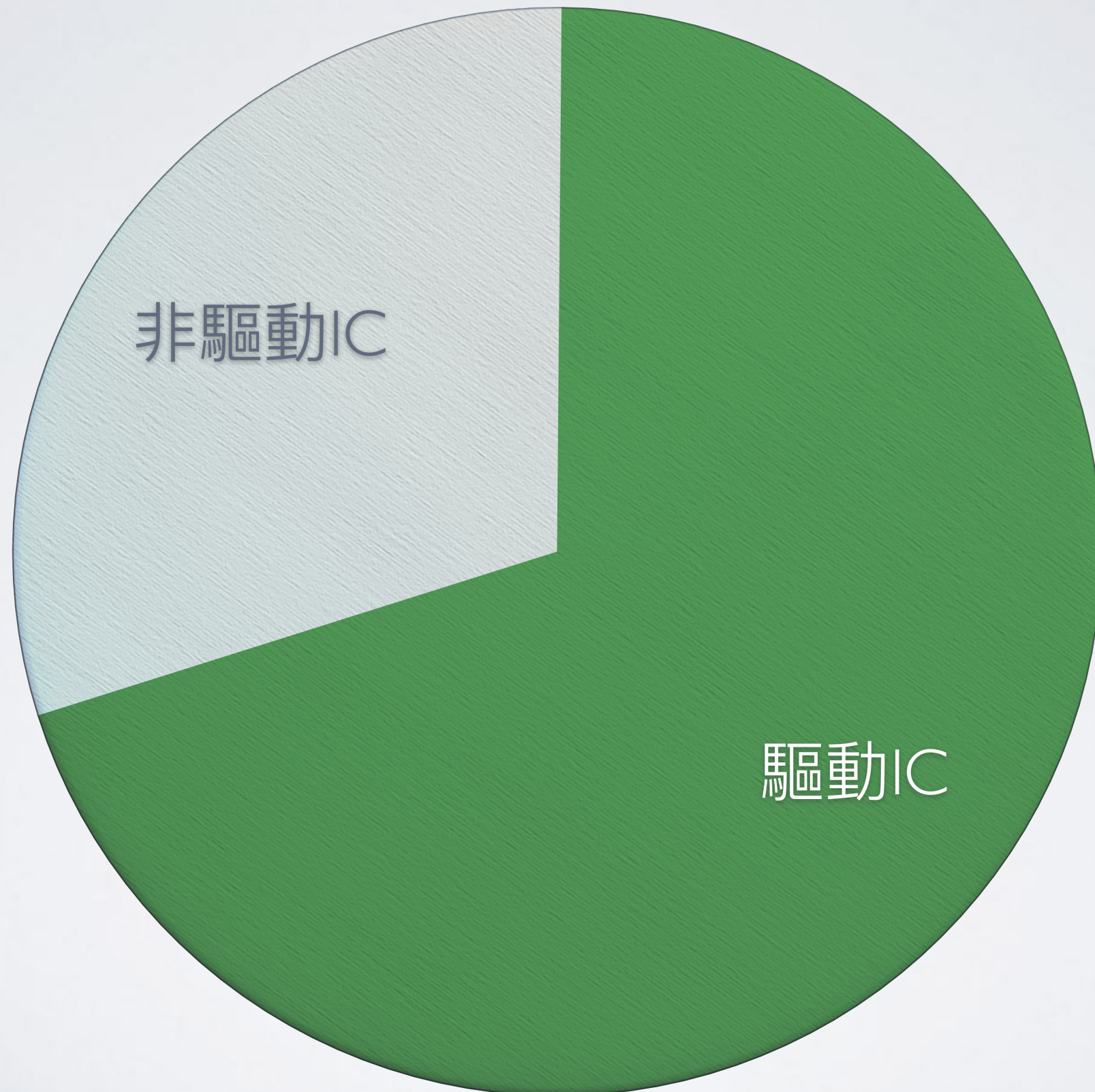
SELLTHROUGH

	2022	2023	2024	2025(F)	Source
TV	180	195	200	200	Samsung / Omdia
NB	180	160	165	180	IDC
SP	1217	1200	1200	1200	GfK

產能利用率



APPLICATIONS



非驅動IC 製程

- 電鍍
- 濺鍍
- 蒸鍍
- 背面金屬化
- 重佈線層

